

# **Pin Descriptions**

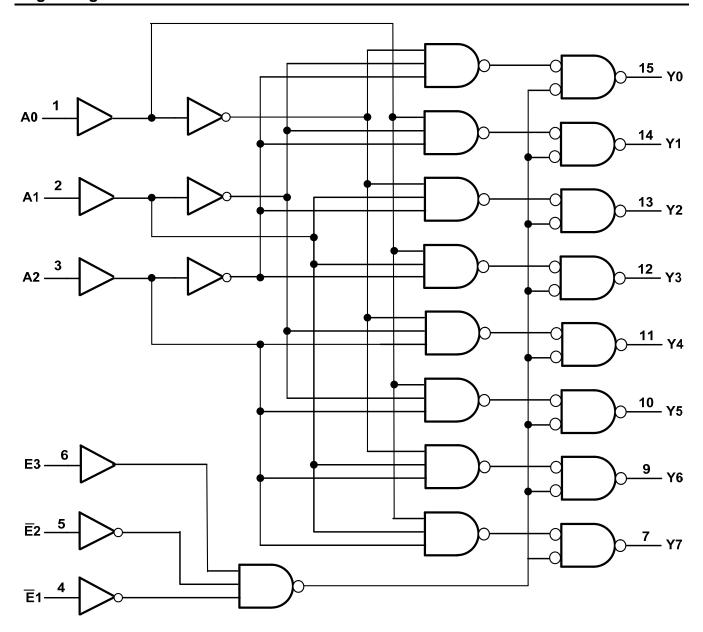
Pin Number	Pin Name	Description
1	A0	Address Input 0
2	A1	Address Input 1
3	A2	Address Input 2
4	<u>E</u> 1	Enable Input 1 (active LOW)
5	E2	Enable Input 2 (active LOW)
6	E3	Enable Input 3 (active HIGH)
7	Y7	Output 7 (active LOW)
8	GND	Ground
9	Y6	Output 6 (active LOW)
10	Y5	Output 5 (active LOW)
11	Y4	Output 4 (active LOW)
12	Y3	Output 3 (active LOW)
13	Y2	Output 2 (active LOW)
14	Y1	Output 1 (active LOW)
15	Y0	Output o (active LOW)
16	V <sub>cc</sub>	Supply Voltage

# **Function Table Diagram**

	Control			Input					Ou	tput			
E <sub>1</sub>	E2	E3	A2	A1	A0	<del>7</del> 7	<del>Y</del> 6	<del>Y</del> 5	₹4	<del>7</del> 3	Y2	<u>Y</u> 1	<del>Y</del> 0
Н	Х	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	Н	Х											
Х	Х	L											
L	L	Н											
			L	L	L	Н	Н	Н	Н	Н	Н	Н	L
			L	L	Н	Н	Н	Н	Н	Н	Н	L	Н
			L	Н	L	Н	Н	Н	Н	Н	L	Н	Н
			L	Н	Н	Н	Н	Н	Н	L	Н	Н	Н
			Н	L	L	Н	Н	Н	L	Н	Н	Н	Н
			Н	L	Н	Н	Н	L	Н	Н	Н	Н	Н
			Н	Н	L	Н	L	Н	Н	Н	Н	Н	Н
			Н	Н	Н	L	Н	Н	Н	Н	Н	Н	Н



# **Logic Diagram**



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# Absolute Maximum Ratings (Note 4) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to 7.0	V
Vı	Input Voltage Range	-0.5 to 7.0	V
Vo	Voltage applied to output in high or low state	-0.3 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < -0.5V	-20	mA
I <sub>OK</sub>	Output Clamp Current V <sub>O</sub> < -0.5V	-20	mA
lok	Output Clamp Current V <sub>O</sub> > V <sub>CC</sub> +0.5 V	20	mA
Io	Continuous output current	+/- 25	mA
I <sub>CC</sub>	Continuous current through V <sub>CC</sub>	75	mA
I <sub>GND</sub>	Continuous current through GND	-75	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

Notes: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

# Recommended Operating Conditions (Note 5) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	Supply Voltage	_	2.0	5.5	V
VI	Input Voltage	-	0	5.5	٧
Vo	Output Voltage	Active Mode	0	V <sub>CC</sub>	V
Δt/ΔV	Input transition rise or fall rate	$V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$	-	100	ns/V
ΔυΔν	input transition rise or fail rate	V <sub>CC</sub> = 5.0 V ± 0.5 V	-	20	115/ V
T <sub>A</sub>	Operating free-air temperature	_	-40	+125	°C

Notes: 5. Unused inputs should be held at  $V_{CC}$  or Ground.



# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

				Т	<sub>A</sub> = +25°	С	-40°C to	+85°C	-40°C t	o +125°C	
Symbol	Parameter	Test Conditions	Vcc	Min	Тур	Max	Min	Max	Min	Max	Unit
		-	2.0V	1.5	-	-	1.5	=	1.5	=	
VIH	High-level Input Voltage	_	3.0V	2.1	_	-	2.1	-	2.1	_	٧
	Vollago	_	5.5V	3.85	_	-	3.85	-	3.85	_	
		-	2.0V	-	_	0.5	-	0.5	-	0.5	
V <sub>IL</sub>	Low-level input voltage	_	3.0V	-	_	0.9	-	0.9	-	0.9	V
	l	_	5.5V	-	_	1.65	-	1.65	-	1.65	
		Ι <sub>ΟΗ</sub> = -50 μΑ	2.0V	1.9	2.0	-	1.9	-	1.9	-	
		I <sub>OH</sub> = -50 μA	3.0V	2.9	3.0	-	2.9	-	2.9	_	
VoH	High Level Output Voltage	Ι <sub>ΟΗ</sub> = -50 μΑ	4.5V	4.4	4.5	-	4.4	-	4.4	_	V
		I <sub>OH</sub> = -4 mA	3.0V	2.58	_	-	2.48	-	2.40	_	
		I <sub>OH</sub> = -8 mA	4.5V	3.94	_	-	3.80	-	3.70	_	
		I <sub>OL</sub> = 50 μA	2.0V	-	_	0.1	-	0.1	-	0.1	
		I <sub>OL</sub> = 50 μA	3.0V	-	_	0.1	-	0.1	-	0.1	
V <sub>OL</sub>	Low-level Output Voltage	I <sub>OL</sub> = 50 μA	4.5V	-	_	0.1	-	0.1	-	0.1	V
		I <sub>OL</sub> = 4 mA	3.0V	-	_	0.36	-	0.44	-	0.55	
		I <sub>OL</sub> = 8 mA	4.5V	-	_	0.36	-	0.44	-	0.55	
l <sub>l</sub>	Input Current	V <sub>I</sub> =GND or 5.5 V	5.5V	-	_	0.1	-	± 1	-	± 2	μA
Icc	Supply Current	$V_1 = GND \text{ or } V_{CC}$ $I_0 = 0 \text{ A}$	5.5V	-	-	4.0	=	40	=	80	μA
Ci	Input Capacitance	$V_i = V_{CC}$ or GND	5.5V	-	4.0	10	=	10	=	10	pF

# **Switching Characteristics**

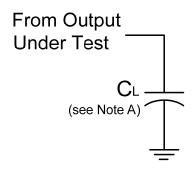
		Test	.,		T <sub>A</sub> = +25°C	<b>.</b>	-40°C to	+85°C	-40°C to	+125°C	
Symbol	Parameter	Conditions	Vcc	Min	Тур.	Max	Min	Max	Min	Max	Unit
		Figure 2	3.0 V to 3.6V	0.5	4.4	8.0	0.5	9.5	0.5	11.5	
	Propagation	C <sub>L</sub> =15 pF	4.5 V to 5.5 V	0.5	3.0	5.5	0.5	6.5	0.5	7.0	
	Delay An to $\overline{Y}$ n	Figure 2	3.0 V to 3.6V	0.5	6.2	11.5	0.5	13.0	0.5	14.5	ns
		C <sub>L</sub> =50pF	4.5 V to 5.5 V	0.5	4.3	7.5	0.5	8.5	0.5	9.5	
	Figure 2	Figure 2	3.0 V to 3.6V	0.5	4.7	8.0	0.5	9.5	0.5	11.5	
	Propagation	gation C <sub>L</sub> =15 pF	4.5 V to 5.5 V	0.5	3.3	5.1	0.5	6.0	0.5	7.5	
t <sub>PD</sub>	Delay E3 to $\overline{Y}$ n	Figure 2	3.0 V to 3.6V	0.5	6.8	11.5	0.5	13.0	0.5	14.5	ns
		C <sub>L</sub> =50pF	4.5 V to 5.5 V	0.5	4.7	7.1	0.5	8.0	0.5	9.0	
	Propagation Delay En to Yn	Figure 2	3.0 V to 3.6V	0.5	6.7	9.7	0.5	11.5	0.5	12.5	
		C <sub>L</sub> =15 pF	4.5 V to 5.5 V	0.5	4.8	6.8	0.5	8.0	0.5	8.5	
		Figure 2	3.0 V to 3.6V	0.5	9.6	13.2	0.5	15.0	0.5	16.5	ns
		C <sub>L</sub> =50pF	4.5 V to 5.5 V	0.5	6.8	8.8	0.5	10.0	0.5	11.0	



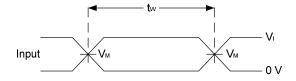
## Operating Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

	Parameter Test Conditions		Parameter Test Conditions		V <sub>CC</sub> = 5 V TYP	Unit
$C_{pd}$	Power dissipation capacitance	f = 1 MHz all outputs switching-no load	18	pF		

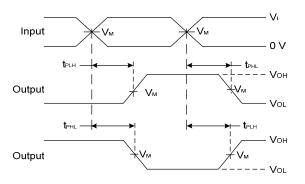
#### **Parameter Measurement Information**



Vee	Inp	outs	V	•
Vcc	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	G <sub>L</sub>
2.0V -6.0V	V <sub>CC</sub>	6ns	V <sub>CC</sub> /2	50pF
5.0V	V <sub>CC</sub>	6ns	V <sub>CC</sub> /2	15pF used for 5V typical test



Voltage Waveform Pulse Duration



Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

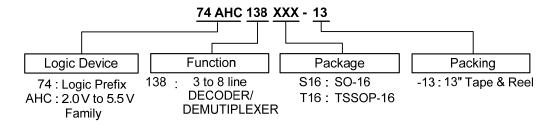
Notes: A . Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 10 MHz
- C. Inputs are measured separately one transition per measurement
- D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD}$

Figure 1. Load Circuit and Voltage Waveforms



## **Ordering Information**

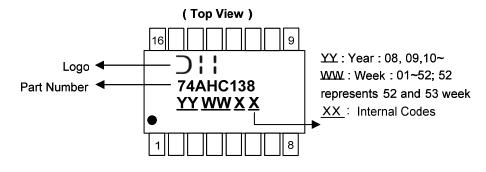


Davise	Backers Cade	Packaging	7" Tape and	Reel (Note 7
Device	Package Code	(Note 6)	Quantity	Part Number Suffix
74AHC138S16-13	S16	SO-16	2500/Tape & Reel	-13
74AHC138T16-13	T16	TSSOP-16	2500/Tape & Reel	-13

 Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <a href="http://www.diodes.com/datasheets/ap02001.pdf">http://www.diodes.com/datasheets/ap02001.pdf</a>
 The taping orientation is located on our website at <a href="http://www.diodes.com/datasheets/ap02007.pdf">http://www.diodes.com/datasheets/ap02007.pdf</a> Notes:

## **Marking Information**

#### (1) SO-16, TSSOP-16



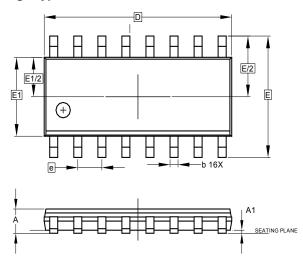
Part Number	Package
74AHC138S16	SO-16
74AHC138T16	TSSOP-16



## Package Outline Dimensions (All Dimensions in mm)

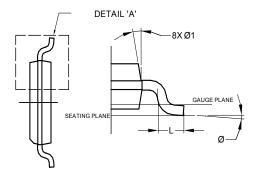
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

#### (1) Package Type: SO-16

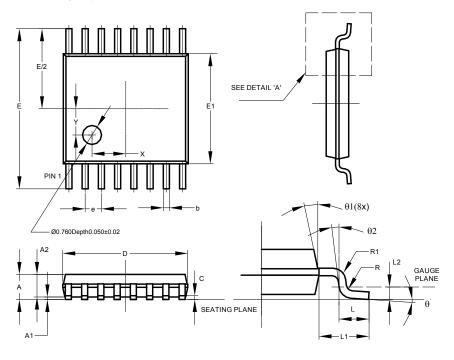


Dim	Min	Max	Тур			
Α	-	1.75	-			
<b>A</b> 1	0.10	0.25	-			
b	0.31	0.51	-			
С	0.10	0.25	-			
D	9.80	10.00	-			
Е	5.80	6.20	-			
E1	3.80	4.00	-			
е	-	-	1.27			
L	0.40	1.27	-			
Ø	0°	8°	-			
Ø1	5°	15°	-			
All Dimensions in mm						

SOIC-16



#### (2) Package Type: TSSOP-16



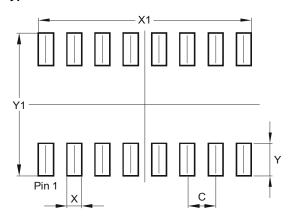
TSSOP-16							
Dim	Min	Max	Тур				
Α	-	1.08	-				
<b>A</b> 1	0.05	0.15	•				
A2	0.80	0.93					
b	0.19	0.30	•				
С	0.09	0.20	•				
D	4.90	5.10	-				
Е	6	.40 BS0					
E1	4.30	4.50	•				
е	C	.65 BS(					
L	0.45	0.75	•				
L1	1	.00 RE	F				
L2	C	.25 BS0					
R	0.09	•	•				
R1	0.09	٠	٠				
Χ	-	-	1.350				
Υ	•	•	1.050				
Θ	0°	8°	•				
91	5°	15°	-				
02	0°	-	-				
All I	Dimensi	ions in ı	mm				



# **Suggested Pad Layout**

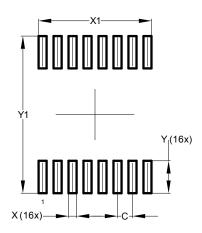
 $Please see AP02001 \ at \ http://www.diodes.com/datasheets/ap02001.pdf \ for \ the \ latest \ version.$ 

#### (1) Package Type: SO-16



Dimensions	Value (in mm)
С	1.270
Х	0.670
X1	9.560
Y	1.450
Y1	6.400

#### (2) Package Type: TSSOP-16



Dimensions	Value (in mm)
С	0.650
Х	0.350
X1	4.900
Υ	1.400
Y1	6.800



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